

MA3SE010G

Silicon epitaxial planar type

For cellular phone

■ Features

- High-frequency wave detection is possible
- Low forward voltage V_F
- Small junction-capacitance

■ Package

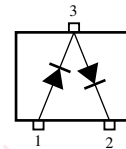
- Code
SSMini3-F3
- Pin Name
1: Anode 1
2: Cathode 2
3: Cathode 1
Anode 2

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	20	V
Maximum peak reverse voltage	V_{RM}	20	V
Forward current	Single	I_F	35
	Series		25
Peak forward current	Single	I_{FM}	100
	Series		70
Junction temperature	T_j	125	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +125	$^\circ\text{C}$

■ Marking Symbol: M6A

■ Internal Connection

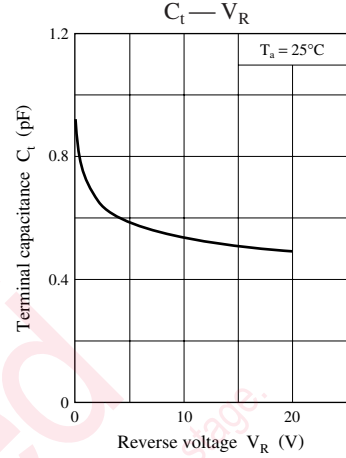
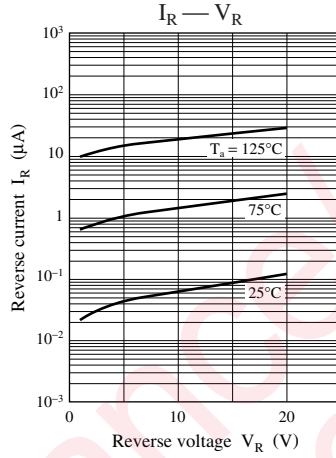
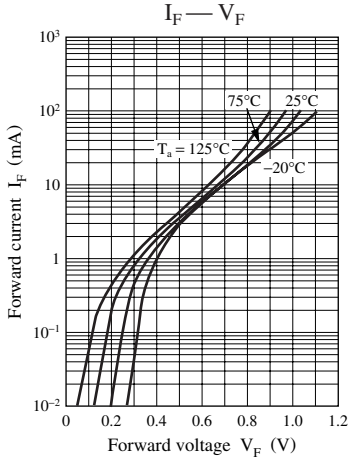


■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_{F1}	$I_F = 1 \text{ mA}$			0.41	V
	V_{F2}	$I_F = 35 \text{ mA}$			1.0	V
Reverse current	I_R	$V_R = 15 \text{ V}$			200	nA
Terminal capacitance	C_t	$V_R = 0 \text{ V}, f = 1 \text{ MHz}$			1.2	pF
Dynamic resistance	R_d	$I_F = 5 \text{ mA}$		40		Ω

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

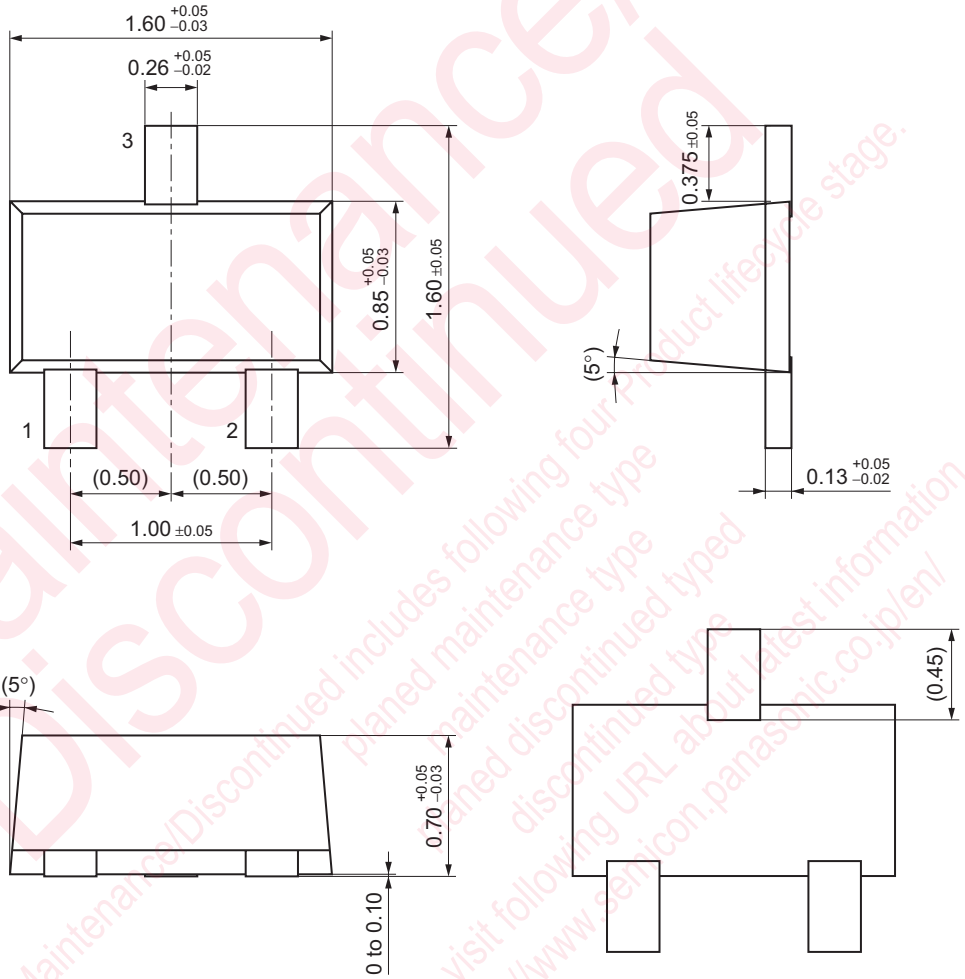
2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
3. Absolute frequency of input and output is 2 GHz



Maintenance/Discontinued includes following four Product lifecycle stage.
 planned maintenance type
 maintenance type
 planned discontinued type
 discontinued type
 Please visit following URL about latest information.
<http://www.semicon.panasonic.co.jp/en/>

SSMini3-F3

Unit: mm



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